

Connector for microSD™ Card (Hinge Cover Type)

SCHB Series



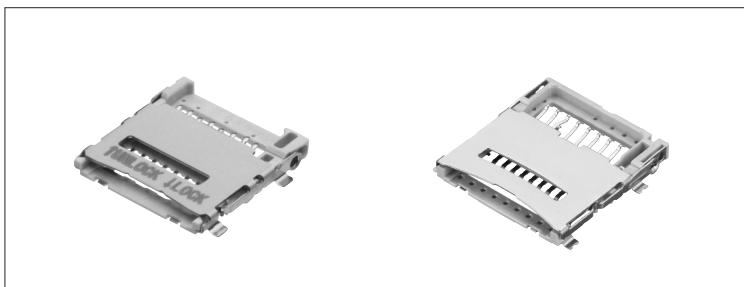
Hinge cover type with improved card retention.

For SD Memory Card

For microSD™ Card

For SIM Card 8pins

For Memory Stick Micro™



Combine Type

For W-SIM

Typical Specifications

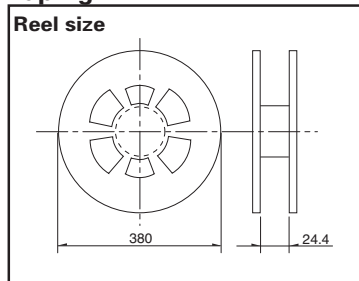
Items		Specifications
Structure	Applicable media	microSD™ Card
	Mounting type	Surface mounting type
	Mounting style	Standard mount
	Media ejection structure	Manual insertion/removal
Performance	Operating temperature range	-20°C to +70°C
	Voltage proof	500V AC 1minute
	Insulation resistance (Initial)	1,000MΩ min.
	Contact resistance (Initial)	100mΩ max.
	Insertion and removal cycle	5,000cycles

Product Line

Media ejection structure	Mounting system	Feature	Stand-off (mm)	Packing system	Product No.	Drawing No.
Manual insertion/removal	Standard mount	Without switch	0	Taping	SCHB1A0205	1
		With switch			SCHB1B0100	2

Packing Specifications

Taping Unit:mm



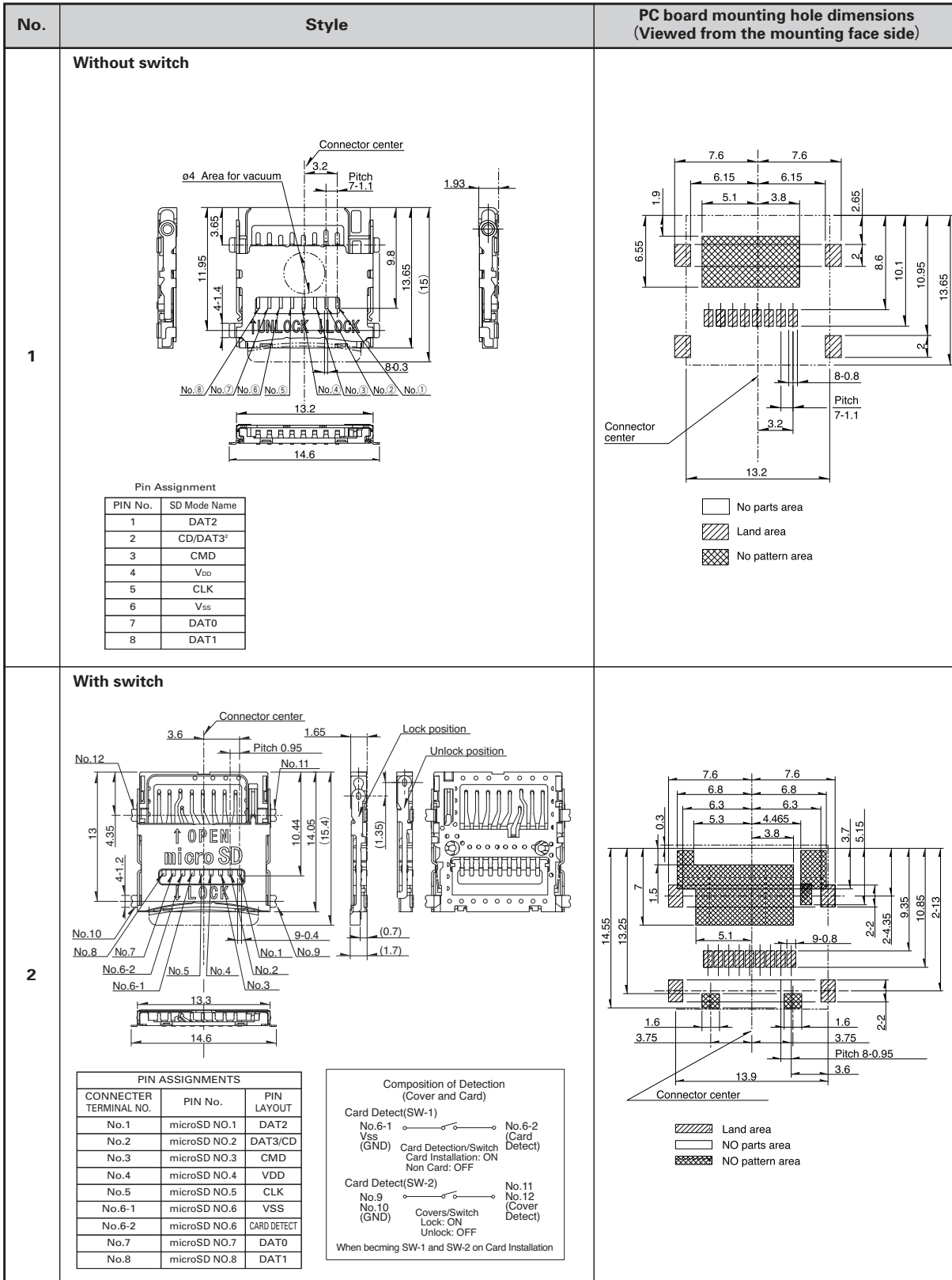
Product No.	Number of packages (pcs.)			Reel width (mm)	Tape width (mm)	Export package measurements (mm)
	1 reel	1 case /Japan	1 case /export packing			
SCHB1A0205	1,400	4,200	8,400	330	24	353×353×249
SCHB1B0100	1,500	4,500	9,000	380		403×403×249

Note

Please place purchase orders per minimum order unit N (integer).

Dimensions

Unit:mm



For SD Memory Card

For microSD™ Card

For SIM Card 8pins







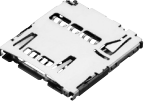







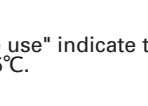
For Memory Stick Micro™

Combine Type

For W-SIM

List of Varieties

- For SD Memory Card
- For microSD™ Card
- For SIM Card 8pins
- For Memory Stick Micro™
- Combine Type
- For W-SIM

Applicable media	Product No.	Photo	Media ejection structure	Mounting style	Features	Stand-off (mm)	Auto motive use	Page
SD Memory Card Multi-MediaCard™	SCDA9A0400		Push-push type	Standard mount	Inner tail Card eject stroke 5mm	0	—	527
	SCDA8A0201				Inner tail Card eject stroke 8mm			
	SCDA7A0101				Card eject stroke 8mm	1.5	○	
	SCDA7A0200			1.8		—		
	SCDA7A1201			Outer tail	0		—	
	SCDAAA0100				1.8			
	SCDAAA0601			Manual insertion/removal	Standard mount	With switch	0	
SCHA4B0100		With switches and fly-out protection.	—					
SCHA4B0400		With switch	○					
SCHA5B0200		Standard mount	Hinge cover type Without switch		0	—	535	
SCHB1A0205			Hinge cover type With switch					
SCHB1B0100		Header type	Standard mount		Header type	—	—	537
SCHD1A0101								
SCHD3A0100		Adapter	—	Adapter	—	—	539	
SCHH1D0100								

Note

○marks in "Available for automotive use" indicate that some of the series products can work at the operating temperature range from -40°C to +85°C.

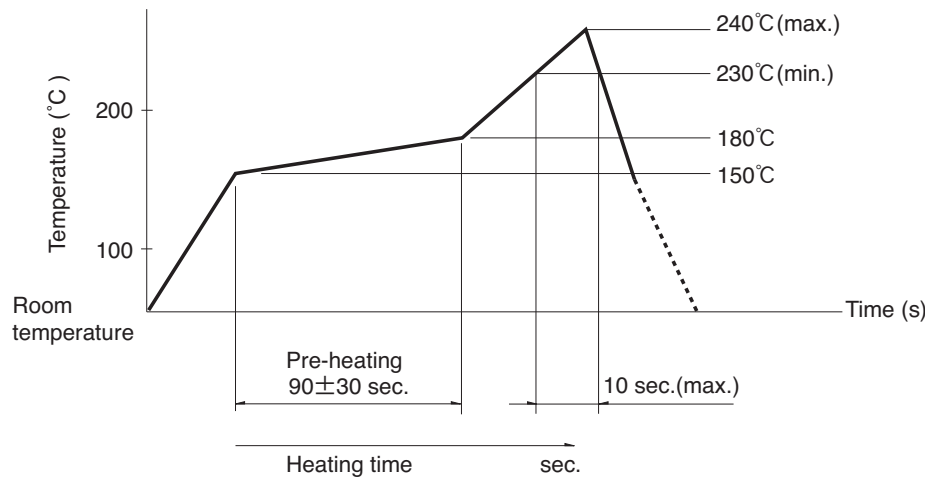
Note

Please place purchase orders per minimum order unit N (integer).

Soldering Conditions

Example of Reflow Soldering Condition (Reference)

1. Heating method: Double heating method with infrared heater.
2. Temperature measurement: Thermocouple 0.1 to 0.2 ϕ CA (K) or CC (T) at soldering portion.
3. Temperature profile



For
SD Memory
Card

For
microSD™
Card

For
SIM Card
8pins

For
Memory
Stick Micro™

Combine Type

For
W-SIM

Please refer to each product's specification sheet to confirm temperature profile.

Cautions for using this product

1.Connector handling precautions

- (1) Safeguard the connector assembly against flux penetration from its top side.
- (2) This product is designed on the assumption that they will not be washed after soldering.

If you wash it, it may cause deterioration of mechanically and electrically.

If washing is necessary, please make contact with us beforehand.

2.When soldering terminals, there is a danger that load placed on the terminals may cause rattle, deformation or electrical degradation to occur depending on the conditions.

Caution is therefore required.

3.When soldering, do not use water soluble flux because this may corrode the product.

4.regarding the setting of reflow conditions, please confirm them with the actual mass production conditions.

5.As P.W.B. warping may alter characteristics, please take this into consideration when designing pattern and layout.

6.Please do not solder at the ejector pushing position.

7.To prevent contact disturbance by the sulfuration or oxidation of the contact and terminal, and deterioration of solder ability by thin film on the terminal, please note following.

- Storage in the atmosphere of high temperature at 60 degrees or more, high humidity, corrosive gases such as sulfur or chlorine gas, and excessive piling up of the carton boxes shall be avoided.
- Connectors shall be stored as the package not opened and in the normal temperature and normal humidity, and the connectors shall be used preferably within 3 months, at least within 6 months.
- When the connectors are stored after opening the package, the connectors shall be sealed with a polyethylene bag etc. and stored in dark and cool place, avoiding direct sunlight. Bag etc. and stored in dark and cool place, avoiding direct sunlight. The connectors shall be used as soon as possible.

8.Don't push or hold down the metal cover of the connector, otherwise there is a possibility that the card would not be ejected or influences to other function.

9.Please attention following items to prevent connector from miss operation, such as bounding caused by ON/OFF switching and chattering by vibration.

- Repeated reading/writing.
- Establish delay time-recommended 400msec min.
- Establish CR accumulation circuit.

10.This product does not operate normally when the card which does not conform to the specification is used occasionally.